

PRODUCT DATA SHEET

677-MG-2

Hot Air Leveling Fluid

Introduction

677-MG-2 Hot Air Leveling Fluid is formulated for use with vertical hot air leveling equipment. The optimized viscosity, high-temperature stable fluid provides excellent thermal conductivity and complete water solubility.

Features

- Provides a uniform solder coating on surface mount and through hole geometries
- Prevents solder skips, solder shorts, and solder spikes
- Protects molten solder from oxidation, eliminating white haze
- Polyglycol-free formulation compatible with all solder masks
- Cleans to low ionic levels with hot water without generating excessive foam
- Good for use with SnPb and Pb-free HASL processes
- VOC-free formulation for easy use

Physical Properties

Test	Result
Appearance	Viscous Liquid
Specific Gravity	1.08
Percent Solids	70
Flash Point	510°F (265°C)
Acid Value	22
Shelf Life	3 years

All information is for reference only.

Not to be used as incoming product specifications.

Process Recommendations

Hot air leveling fluid is commonly applied with the use of nappy-type rollers. The rollers should force fluid into the plated through holes and remove excess fluid.

- For SnPb process: use 450°F (232°C) solder temperature or lower. Dwell time 2–3 seconds
- For Pb-free process: use 530°F (277°C) solder temperature or lower. Dwell time 4–6 seconds

This product data sheet is provided for general information only. It is not intended, and shall not be construed, to warrant or guarantee the performance of the products described which are sold subject exclusively to written warranties and limitations thereon included in product packaging and invoices. All Indium Corporation's products and solutions are designed to be commercially available unless specifically stated otherwise.

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

From One Engineer To Another®

Contact our engineers: askus@indium.com

Learn more: www.indium.com

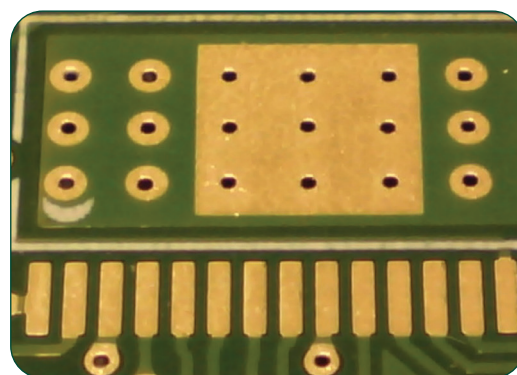
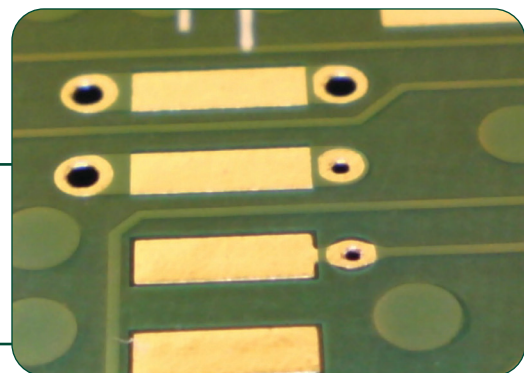
ASIA +65 6268 8678 • CHINA +86 (0) 512 628 34900 • EUROPE +44 (0) 1908 580400 • USA +1 315 853 4900



Form No. 100358 R0



©2026 Indium Corporation



Air knife angle should be 45°. A high withdrawal speed using a close air knife gap at correct pressure will provide the most uniform solder surface. Maintain solder pot tin and copper content for the best results.

Technical Support

Indium Corporation's internationally experienced engineers provide in-depth technical assistance to our customers. Thoroughly knowledgeable in all facets of Materials Science as it applies to the electronics and semiconductor sectors, Technical Support Engineers provide expert advice in solder properties, alloy compatibility and selection of solder preforms, wire, ribbon, and paste. Indium Corporation's Technical Support Engineers provide rapid response to all technical inquiries.

Safety Data Sheets

Please refer to the SDS document within the product shipment, or contact our local team to receive a copy.